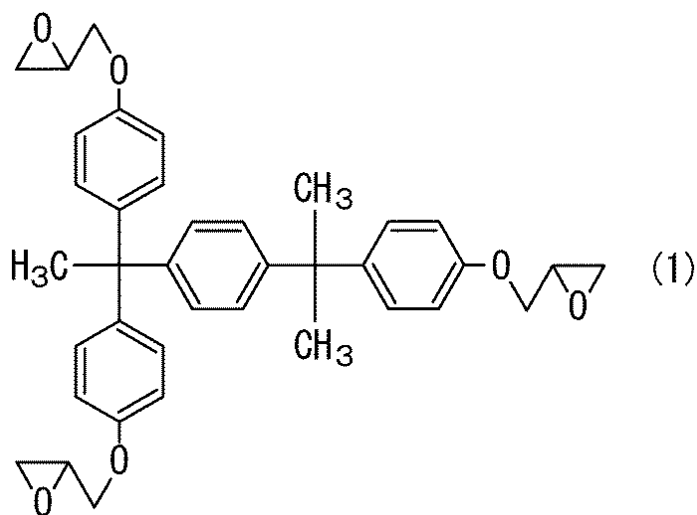


ABSTRACT

The present invention relates to an adhesive sheet for producing a semiconductor device. In the adhesive sheet for producing a semiconductor device which includes a substrate, and a thermo-setting type adhesive layer provided on one surface of the substrate mentioned above, and which is releasably adhered to a wiring substrate or a lead frame of the semiconductor device, the adhesive layer mentioned above contains (a) a carboxyl group-containing acrylonitrile – butadiene copolymer, (b) an epoxy resin having the following structural formula (1), (c) a compound having two or more maleimide groups, and (d) a reactive siloxane compound. In addition, the present invention provides a method for producing a semiconductor device using the adhesive sheet mentioned above.



15 [Figure 2]